

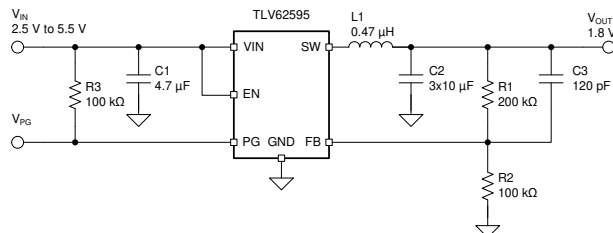
TLV62595, 2.5-V to 5.5-V Input, 4-A Step-Down Converter with 1% Output Accuracy in 1.5-mm × 1.5-mm QFN Package

1 Features

- Up to 97% efficiency
- Low $R_{DS(ON)}$ power switches 26 mΩ / 25 mΩ
- 2.5-V to 5.5-V input voltage range
- Adjustable output voltage from 0.6 V to 4 V
- 1% feedback voltage accuracy (full temperature range)
- DCS-control topology
- Power save mode for light load efficiency
- 100% duty cycle for lowest dropout
- 10-μA operating quiescent current
- 2.2-MHz typical switching frequency
- Short circuit protection (HICCUP)
- Active output discharge
- Power good output
- Thermal shutdown protection
- Create a custom design using the TLV62595 with the [WEBENCH® Power Designer](#)

2 Applications

- [Solid state drive](#)
- [Portable electronics](#)
- [IP network camera](#)
- [Industrial PC](#)
- [Multifunction printers](#)



Typical Application Schematic

3 Description

The TLV62595 is a high-frequency synchronous step-down converter optimized for compact solution size and high efficiency. The device integrates switches capable of delivering an output current up to 4 A. At medium to heavy loads, the converter operates in pulse width modulation (PWM) mode with typical 2.2-MHz switching frequency. At light load, the device automatically enters Power Save Mode (PSM) to maintain high efficiency over the entire load current range with a quiescent current as low as 10 μA.

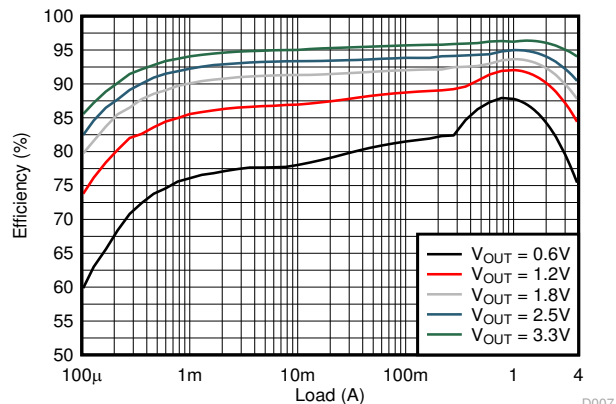
Based on the DCS Control topology, the device provides a fast transient response. The internal reference regulates the output voltage down to 0.6 V with a high feedback voltage accuracy of 1% over the junction temperature range of -40°C to 125°C . The entire solution requires a small 470-nH inductor, a single 4.7-μF input capacitor and three 10-μF or single 47-μF output capacitor.

The device is available in a 6-pin 1.5-mm × 1.5-mm QFN package, offering a high power density solution.

Package Information

PART NUMBER	PACKAGE ⁽¹⁾	BODY SIZE (NOM)
TLV62595	DMQ (VSON-HR, 6)	1.50 mm × 1.50 mm

- (1) For all available packages, see the orderable addendum at the end of the data sheet.



Efficiency at $V_{IN} = 5\text{ V}$



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4 Revision History

Changes from Revision * (December 2020) to Revision A (January 2023)	Page
• Updated ESD Ratings.....	6
• Removed duplicate table in <i>Output Filter Design</i> section.....	11

5 Pin Configuration and Functions

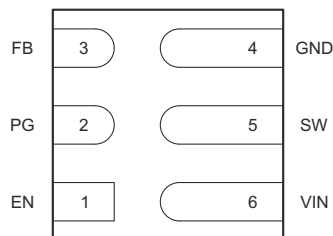


Figure 5-1. 6-Pin VSON-HR DMQ Package (Bottom View)

Table 5-1. Pin Functions

PIN		I/O	DESCRIPTION
NAME	NO.		
EN	1	I	Device enable pin. To enable the device, this pin must be pulled high. Pulling this pin low disables the device. Do not leave floating.
PG	2	O	Power-good open-drain output pin. The pullup resistor can be connected to voltages up to 5.5 V. If unused, leave this pin floating.
FB	3	I	Feedback pin. For the fixed output voltage versions, this pin must be connected to the output.
GND	4		Ground pin
SW	5	PWR	Switch pin of the power stage
VIN	6	PWR	Input voltage pin

6 Specifications

6.1 Absolute Maximum Ratings

over operating temperature range (unless otherwise noted)⁽¹⁾

		MIN	MAX	UNIT
Pin voltage ⁽²⁾	VIN, FB, EN, PG	– 0.3	6	V
Pin voltage ⁽²⁾	SW (DC)	– 0.3	VIN + 0.3	V
Pin voltage ⁽²⁾	SW (DC, in current limit)	– 1	VIN + 0.3	
Pin voltage ⁽²⁾	SW (AC, less than 10ns) ⁽³⁾	– 2.5	10	V
Temperature	Operating Junction, TJ	–40	150	°C
Temperature	Storage, TSTG	–65	150	°C

- (1) Stresses beyond those listed under *Absolute Maximum Rating* may cause permanent damage to the device. These are stress ratings only, which do not imply functional operation of the device at these or any other conditions beyond those indicated under *Recommended Operating Condition*. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.
- (2) All voltage values are with respect to the network ground terminal
- (3) While switching

6.2 ESD Ratings

			VALUE	UNIT
V(ESD)	Electrostatic discharge	Human body model (HBM), per ANSI/ESDA/JEDEC JS-001 ⁽¹⁾	±2000	V
		Charged device model (CDM), per ABSI/ESDA/JEDEC JS-002 ⁽²⁾	±500	

- (1) JEDEC document JEP155 states that 500-V HBM allows safe manufacturing with a standard ESD control process.
- (2) JEDEC document JEP157 states that 250-V CDM allows safe manufacturing with a standard ESD control process.

6.3 Recommended Operating Conditions

Over operating temperature range (unless otherwise noted)

		MIN	NOM	MAX	UNIT
VIN	Input voltage range	2.5		5.5	V
VOU	Output voltage range	0.6		4.0	V
IOU	Output current range	0		4	A
VPG	Pull-up resistor voltage			5.5	V
ISINK_PG	Sink current at PG pin			1	mA
TJ	Operating junction temperature	–40		125	°C

6.4 Thermal Information

THERMAL METRIC ⁽¹⁾		TLV62595	TLV62595EVM-794	UNIT
		DMQ (JEDEC)	DMQ (EVM)	
		6 PINS	6 PINS	
RθJA	Junction-to-ambient thermal resistance	129.5	71.4	°C/W
RθJC(top)	Junction-to-case (top) thermal resistance	103.9	n/a	°C/W
RθJB	Junction-to-board thermal resistance	33.1	n/a	°C/W
ΨJT	Junction-to-top characterization parameter	3.8	3.9	°C/W
ΥJB	Junction-to-board characterization parameter	33.1	38.6	°C/W

- (1) For more information about traditional and new thermal metrics, see the [Semiconductor and IC Package Thermal Metrics](#) application report.

6.5 Electrical Characteristics

$T_J = 25\text{ }^{\circ}\text{C}$ and $V_{IN} = 5\text{ V}$, unless otherwise noted.

PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT
SUPPLY						
I _Q	Quiescent current	EN = High, no load, device not switching	10			μA
I _{SD}	Shutdown current	EN = Low, T _J = -40 °C to 85 °C	0.05			μA
V _{UVLO}	Under voltage lock out threshold	V _{IN} falling	2.1	2.2	2.3	V
	Under voltage lock out hysteresis	V _{IN} rising	160			mV
T _{JSD}	Thermal shutdown threshold	T _J rising	150			°C
	Thermal shutdown hysteresis	T _J falling	20			°C
LOGIC INTERFACE EN						
V _{IH}	High-level threshold voltage	V _{IN} = 2.5 V to 5.5 V	1.0			V
V _{IL}	Low-level threshold voltage	V _{IN} = 2.5 V to 5.5 V	0.4			V
SOFT START, POWER GOOD						
t _{SS}	Soft start time	Time from EN high to 95% of V _{OUT} nominal	1.75			ms
V _{PG}	Power good lower threshold	V _{PG} rising, V _{FB} referenced to V _{FB} nominal	96			%
		V _{PG} falling, V _{FB} referenced to V _{FB} nominal	92			%
	Power good upper threshold	V _{PG} rising, V _{FB} referenced to V _{FB} nominal	105			%
		V _{PG} falling, V _{FB} referenced to V _{FB} nominal	110			%
V _{PG,OL}	Low-level output voltage	I _{sink} = 1 mA	0.4			V
I _{PG,LKG}	Input leakage current into PG pin	V _{PG} = 5.0 V	0.01			μA
t _{PG,DLY}	Power good deglitch delay	PG rising edge	100			μs
		PG falling edge	20			
OUTPUT						
V _{FB}	Feedback regulation voltage	PWM mode, 2.5 V ≤ V _{IN} ≤ 5.5 V, T _J = -40°C to 125°C	594	600	606	mV
I _{FB,LKG}	Feedback input leakage current for adjustable output voltage	V _{FB} = 0.6 V	0.01			μA
I _{DIS}	Output discharge current	V _{SW} = 0.4V; EN = LOW	400			mA
	Load regulation	I _{OUT} = 0.5 A to 3 A, V _{OUT} = 1.8 V	0.1			%/A
POWER SWITCH						
R _{DS(on)}	High-side FET on-resistance		26			mΩ
	Low-side FET on-resistance		25			mΩ
I _{LIM}	High-side FET switch current limit, DC		4.8	5.6		A
f _{SW}	PWM switching frequency	I _{OUT} = 1 A, V _{OUT} = 1.8 V	2.2			MHz

6.6 Typical Characteristics

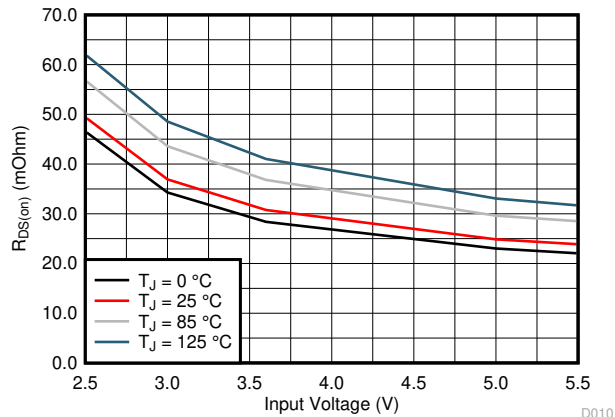


Figure 6-1. High-Side FET On-Resistance

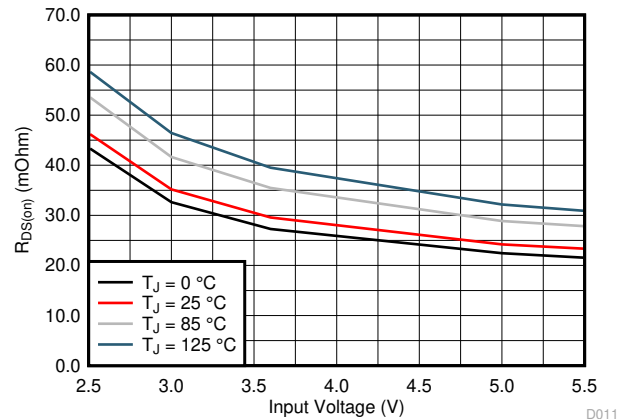


Figure 6-2. Low-Side FET On-Resistance

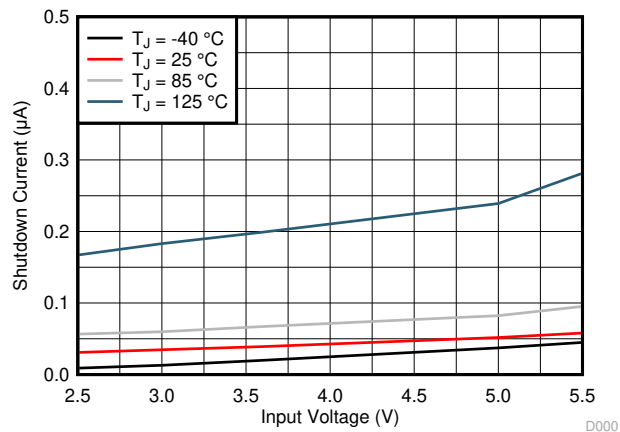


Figure 6-3. Shutdown Current

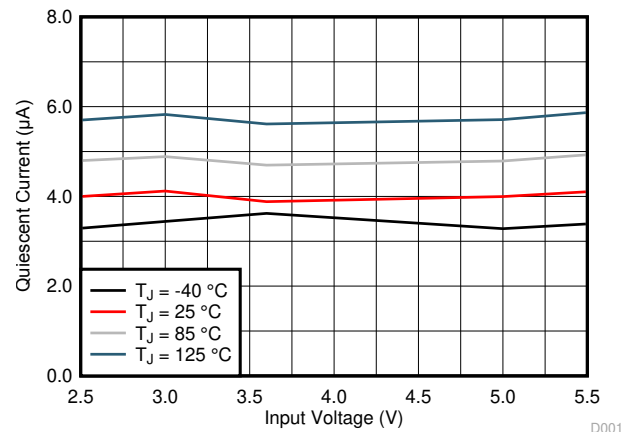


Figure 6-4. Quiescent Current

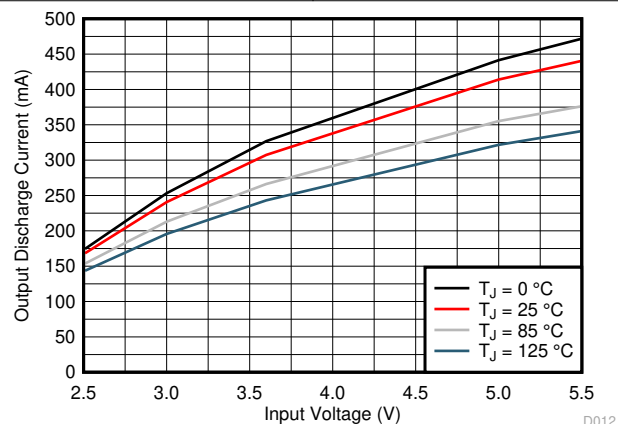


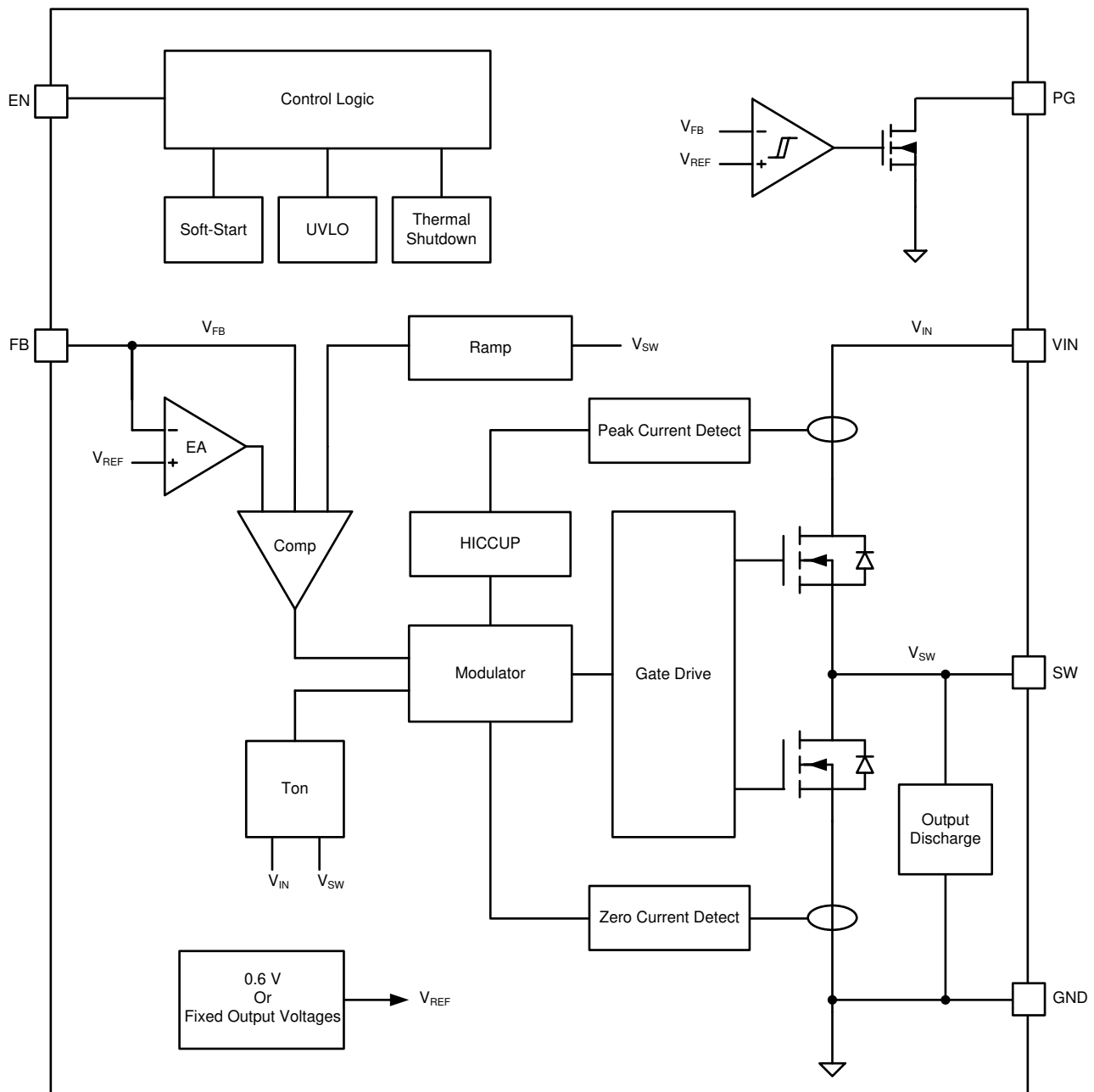
Figure 6-5. Output Discharge Current

7 Detailed Description

7.1 Overview

The TLV62595 are synchronous step-down converters based on the DCS-Control topology with an adaptive constant on-time control and a stabilized switching frequency. The devices operate in PWM (pulse width modulation) mode for medium to heavy loads and in PSM (power save mode) at light load conditions, keeping the output voltage ripple small. The nominal switching frequency is about 2.2 MHz with a small and controlled variation over the input voltage range. As the load current decreases, the converter enters PSM, reducing the switching frequency to keep efficiency high over the entire load current range. Since combining both PWM and PSM within a single building block, the transition between modes is seamless and without effect on the output voltage. The devices offer both excellent dc voltage and fast load transient regulation, combined with a very low output voltage ripple.

7.2 Functional Block Diagram



7.3 Feature Description

7.3.1 Pulse Width Modulation (PWM) Operation

At load currents larger than half the inductor ripple current, the device operates in pulse width modulation in continuous conduction mode (CCM). The PWM operation is based on an adaptive constant on-time control with stabilized switching frequency. To achieve a stable switching frequency in a steady state condition, the on-time is calculated as:

$$T_{ON} = \frac{V_{OUT}}{V_{IN}} \cdot 450ns \quad (1)$$

7.3.2 Power Save Mode (PSM) Operation

To maintain high efficiency at light loads, the device enters power save mode (PSM) at the boundary to discontinuous conduction mode (DCM). This happens when the output current becomes smaller than half of the ripple current of the inductor. The device operates now with a fixed on-time and the switching frequency further decreases proportionally to the load current. It can be calculated as:

$$f_{PSM} = \frac{2 \cdot I_{OUT}}{T_{ON}^2 \cdot \frac{V_{IN}}{V_{OUT}} \left[\frac{V_{IN} - V_{OUT}}{L} \right]} \quad (2)$$

In PSM, the output voltage rises slightly above the nominal target, which can be minimized using larger output capacitance. At duty cycles larger than 90%, the device may not enter PSM. The device maintains output regulation in PWM mode.

7.3.3 Minimum Duty Cycle and 100% Mode Operation

There is no limitation for small duty cycles, because even at very low duty cycles, the switching frequency is reduced as needed to always ensure a proper regulation.

If the output voltage level comes close to the input voltage, the device enters 100% mode. While the high-side switch is constantly turned on, the low-side switch is switched off. The difference between VIN and VOUT is determined by the voltage drop across the high-side FET and the dc resistance of the inductor. The minimum VIN that is needed to maintain a specific VOUT value is estimated as:

$$V_{IN,MIN} = V_{OUT} + I_{OUT,MAX} \times (R_{DS(on)} + R_L) \quad (3)$$

where

- $V_{IN,MIN}$ = Minimum input voltage to maintain an output voltage
- $I_{OUT,MAX}$ = Maximum output current
- $R_{DS(on)}$ = High-side FET ON-resistance
- R_L = Inductor ohmic resistance (DCR)

7.3.4 Soft Start

About 250 μ s after EN goes high, the internal soft-start circuitry controls the output voltage during start-up. This avoids excessive inrush current and ensures a controlled output voltage ramp. It also prevents unwanted voltage drops from high-impedance power sources or batteries. The TLV62595 can start into a pre-biased output.

7.3.5 Switch Current Limit and HICCUP Short-Circuit Protection

The switch current limit prevents the device from drawing excessive current in case of externally-caused overcurrent or short circuit condition. Due to an internal propagation delay (typically 60 ns), the actual ac peak current can exceed the static current limit during that time.

If the current limit threshold is reached, the device delivers its maximum output current. Detecting this condition for 32 switching cycles (about 13 μ s), the device turns off the high-side MOSFET for about 100 μ s which allows

the inductor current to decrease through the low-side MOSFET body diode and then restart again with a soft start cycle. As long as the overload condition is present, the device hiccups that way, limiting the output power.

7.3.6 Undervoltage Lockout

The undervoltage lockout (UVLO) function prevents misoperation of the device, if the input voltage drops below the UVLO threshold. It is set to about 2.2 V with a hysteresis of typically 160 mV.

7.3.7 Thermal Shutdown

The junction temperature (T_J) of the device is monitored by an internal temperature sensor. If T_J exceeds 150°C (typical), the device goes in thermal shutdown with a hysteresis of typically 20°C. After the T_J has decreased enough, the device resumes normal operation.

7.4 Device Functional Modes

7.4.1 Enable, Disable and Output Discharge

The device starts operation, when Enable (EN) is set High. The input threshold levels are typically 0.9 V for rising and 0.7 V for falling signals. Do not leave EN floating. Shutdown is forced if EN is pulled low with a shutdown current of typically 50 nA. During shutdown, the internal power MOSFETs as well as the entire control circuitry, are turned off and the output voltage is actively discharged through the SW pin by a current sink. Therefore VIN must remain present for the discharge to function.

7.4.2 Power Good

The TLV62595 has a built-in power good (PG) function. The PG pin goes high impedance, when the output voltage has reached its nominal value. Otherwise, including when disabled, in UVLO or in thermal shutdown, PG is low (see [Table 7-1](#)). The PG function is formed with a window comparator, which has an upper and lower voltage threshold. The PG pin is an open-drain output and is specified to sink up to 1 mA. The power good output requires a pullup resistor connecting to any voltage rail less than 5.5 V.

The PG signal can be used for sequencing of multiple rails by connecting it to the EN pin of other converters. Leave the PG pin unconnected when not used. The PG rising edge has a 100-μs blanking time and the PG falling edge has a deglitch delay of 20 μs.

Table 7-1. PG Pin Logic

DEVICE CONDITIONS		LOGIC STATUS	
		HIGH Z	LOW
Enable	EN = High, $V_{FB} \geq 0.576$ V	√	
	EN = High, $V_{FB} \leq 0.552$ V		√
	EN = High, $V_{FB} \leq 0.63$ V	√	
	EN = High, $V_{FB} \geq 0.66$ V		√
Shutdown	EN = Low		√
Thermal Shutdown	$T_J > T_{JSD}$		√
UVLO	$0.7 \text{ V} < V_{IN} < V_{UVLO}$		√
Power Supply Removal	$V_{IN} < 0.7$ V	√	

8 Application and Implementation

Note

Information in the following applications sections is not part of the TI component specification, and TI does not warrant its accuracy or completeness. TI's customers are responsible for determining suitability of components for their purposes, as well as validating and testing their design implementation to confirm system functionality.

8.1 Application Information

The following section discusses the design of the external components to complete the power supply design for several input and output voltage options by using typical applications as a reference.

8.2 Typical Application

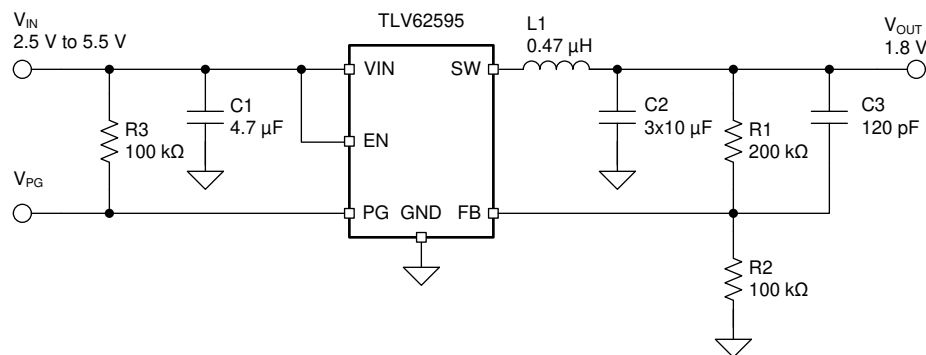


Figure 8-1. Typical Application of TLV62595

8.2.1 Design Requirements

For this design example, use the parameters listed in [Table 8-1](#) as the input parameters.

Table 8-1. Design Parameters

DESIGN PARAMETER	EXAMPLE VALUE
Input voltage, TLV62595	2.5 V to 5.5 V
Output voltage	1.8 V
Output ripple voltage	< 20 mV
Maximum output current, TLV62595	4 A

[Table 8-2](#) lists the components used for the example.

Table 8-2. List of Components

REFERENCE	DESCRIPTION	MANUFACTURER
C1	4.7 μF, Ceramic capacitor, 6.3 V, X7R, size 0603, JMK107BB7475MA	Taiyo Yuden
C2	3 × 10 μF, Ceramic capacitor, 10 V, X7R, size 0603, GRM188Z71A106MA73D	Murata
C3	120 pF, Ceramic capacitor, 50 V, size 0402	Std
L1	0.47 μH, Power Inductor, XFL4015-471MEB	Coilcraft
R1	Depending on the output voltage, 1%, size 0402	Std
R2	100 kΩ, Chip resistor, 1/16 W, 1%, size 0402	Std
R3	100 kΩ, Chip resistor, 1/16 W, 1%, size 0402	Std

- See the [Third-Party Products Disclaimer](#).

8.2.2 Detailed Design Procedure

8.2.2.1 Custom Design With WEBENCH® Tools

[Click here](#) to create a custom design using the TLV62595 device with the WEBENCH® Power Designer.

1. Start by entering the input voltage (V_{IN}), output voltage (V_{OUT}), and output current (I_{OUT}) requirements.
2. Optimize the design for key parameters such as efficiency, footprint, and cost using the optimizer dial.
3. Compare the generated design with other possible solutions from Texas Instruments.

The WEBENCH Power Designer provides a customized schematic along with a list of materials with real-time pricing and component availability.

In most cases, these actions are available:

- Run electrical simulations to see important waveforms and circuit performance
- Run thermal simulations to understand board thermal performance
- Export customized schematic and layout into popular CAD formats
- Print PDF reports for the design, and share the design with colleagues

Get more information about WEBENCH tools at www.ti.com/WEBENCH.

8.2.2.2 Setting The Output Voltage

The output voltage is set by an external resistor divider according to [Equation 4](#):

$$R1 = R2 \times \left(\frac{V_{OUT}}{V_{FB}} - 1 \right) = R2 \times \left(\frac{V_{OUT}}{0.6V} - 1 \right) \quad (4)$$

$R2$ must not be higher than 100 k Ω to achieve high efficiency at light load while providing acceptable noise sensitivity. [Equation 5](#) shows how to compute the value of the feedforward capacitor for a given $R2$ value. For the recommended 100 k value for $R2$, a 120-pF feedforward capacitor is used.

$$C3 = \frac{12\mu}{R2} \quad (5)$$

For the fixed output voltage versions, connect the FB pin to the output. $R1$, $R2$, and $C3$ are not needed. The fixed output voltage devices have an internal feedforward capacitor.

8.2.2.3 Output Filter Design

The inductor and the output capacitor together provide a low-pass filter. To simplify this process, [Table 8-3](#) outlines possible inductor and capacitor value combinations for most applications. Checked cells represent combinations that are proven for stability by simulation and lab test. Further combinations must be checked for each individual application.

Table 8-3. Matrix of Output Capacitor and Inductor Combinations, TLV62595

NOMINAL L [μ H] ⁽²⁾	NOMINAL C_{OUT} [μ F] ⁽³⁾			
	22	3 x 10	47	100
0.33				
0.47		+(1)	+	+
1.0				

(1) This LC combination is the standard value and recommended for most applications.

(2) Inductor tolerance and current derating is anticipated. The effective inductance can vary by 20% and –30%.

(3) Capacitance tolerance and bias voltage derating is anticipated. The effective capacitance can vary by 20% and –35%.

8.2.2.4 Inductor Selection

The main parameter for the inductor selection is the inductor value and then the saturation current of the inductor. To calculate the maximum inductor current under static load conditions, [Equation 6](#) is given.

$$I_{L,MAX} = I_{OUT,MAX} + \frac{\Delta I_L}{2}$$

$$\Delta I_L = V_{OUT} \times \frac{1 - \frac{V_{OUT}}{V_{IN}}}{L \times f_{SW}} \quad (6)$$

where

- $I_{OUT,MAX}$ = Maximum output current
- ΔI_L = Inductor current ripple
- f_{SW} = Switching frequency
- L = Inductor value

TI recommends to choose a saturation current for the inductor that is approximately 20% to 30% higher than $I_{L,MAX}$. In addition, DC resistance and size must also be taken into account when selecting an appropriate inductor. [Table 8-4](#) lists recommended inductors.

Table 8-4. List of Recommended Inductors

INDUCTANCE [μH]	CURRENT RATING [A]	DIMENSIONS [L x W x H mm]	MAX. DC RESISTANCE [mΩ]	MFR PART NUMBER ⁽¹⁾
0.47	4.8	2.0 × 1.6 × 1.0	32	HTEN20161T-R47MDR, Cyntec
	4.6	2.0 × 1.2 × 1.0	25	HTEH20121T-R47MSR, Cyntec
	4.8	2.0 × 1.6 × 1.0	32	DFE201610E - R47M, MuRata
	4.8	2.0 × 1.6 × 1.0	32	DFE201210S - R47M, MuRata
	5.1	2.0 × 1.6 × 1.0	34	TFM201610ALM-R47MTAA, TDK
	5.2	2.0 × 1.6 × 1.0	25	TFM201610ALC-R47MTAA, TDK
	6.6	4.0 × 4.0 × 1.6	8.36	XFL4015-471ME, Coilcraft
	8.0	3.5 × 3.2 × 2.0	10.85	XEL3520-471ME, Coilcraft
	6.8	4.5 × 4 × 1.8	11.2	WE-LHMI-744373240047, Würth

(1) See [Third-party Products Disclaimer](#).

8.2.2.5 Capacitor Selection

The input capacitor is the low-impedance energy source for the converters which helps to provide stable operation. A low-ESR multilayer ceramic capacitor is recommended for best filtering and must be placed between VIN and GND as close as possible to those pins. For most applications, a minimum effective input capacitance of 3 μF must be present, though a larger value reduces input current ripple.

The architecture of the device allows the use of tiny ceramic output capacitors with low equivalent series resistance (ESR). These capacitors provide low output voltage ripple and are recommended. To keep its low resistance up to high frequencies and to get narrow capacitance variation with temperature, TI recommends using X7R or X5R dielectrics. Considering the DC-bias derating the capacitance, the minimum effective output capacitance is 20 μF for TLV62595.

A feedforward capacitor is required for the adjustable version, as described in [Section 8.2.2.2](#). This capacitor is not required for the fixed output voltage versions.

8.2.3 Application Curves

$V_{IN} = 5.0\text{ V}$, $V_{OUT} = 1.8\text{ V}$, $T_A = 25^\circ\text{C}$, BOM = [Table 8-2](#), unless otherwise noted.

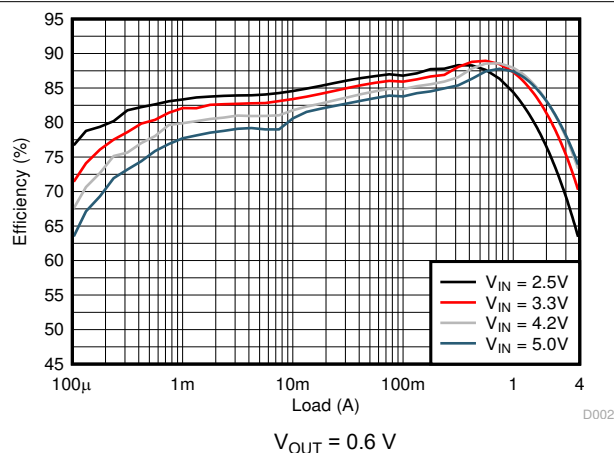


Figure 8-2. Efficiency

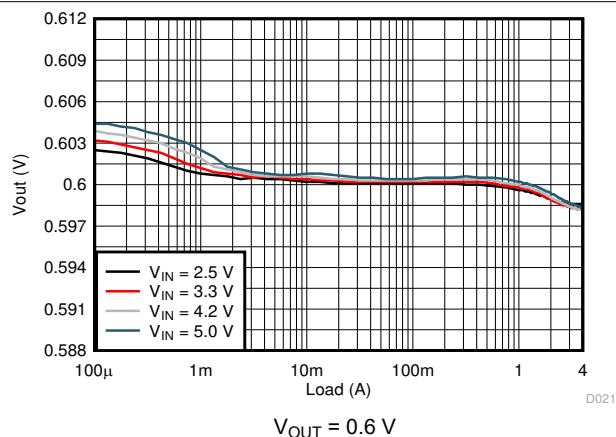


Figure 8-3. Load Regulation

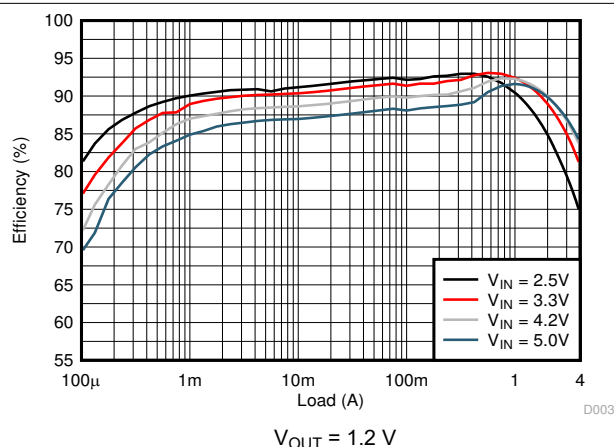


Figure 8-4. Efficiency

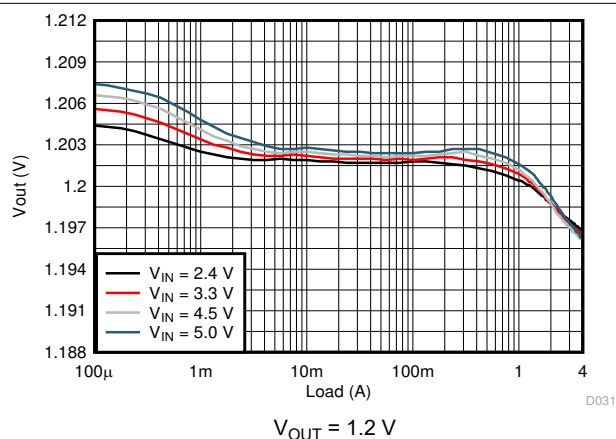


Figure 8-5. Load Regulation

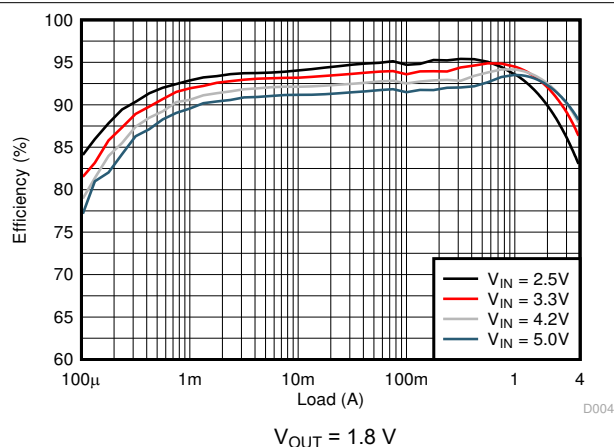


Figure 8-6. Efficiency

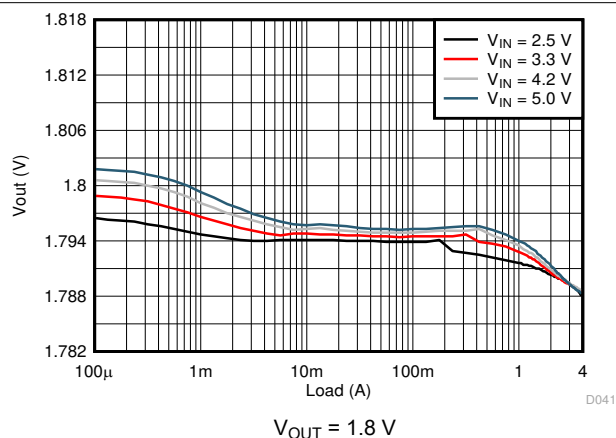


Figure 8-7. Load Regulation

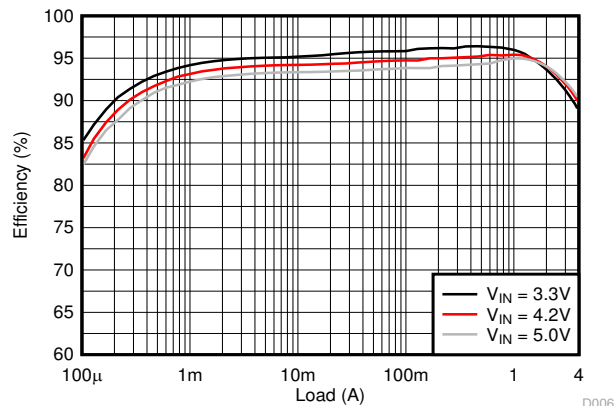


Figure 8-8. Efficiency

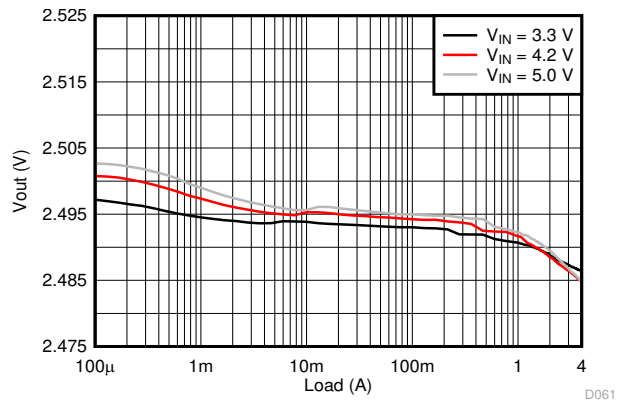


Figure 8-9. Load Regulation

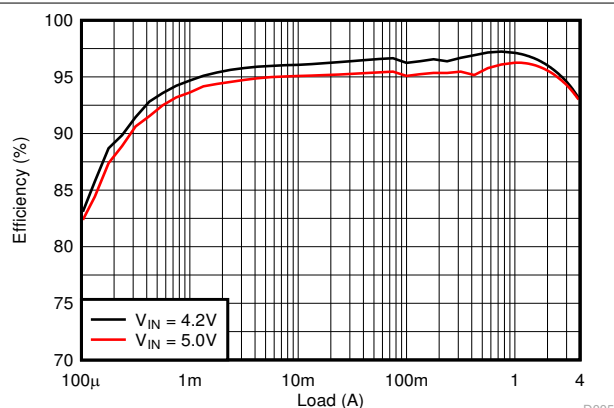


Figure 8-10. Efficiency

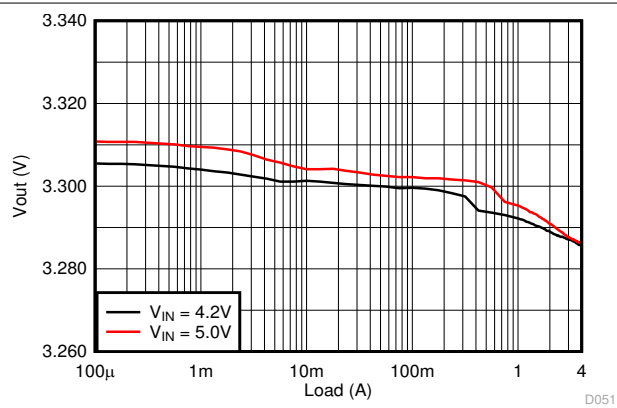


Figure 8-11. Load Regulation

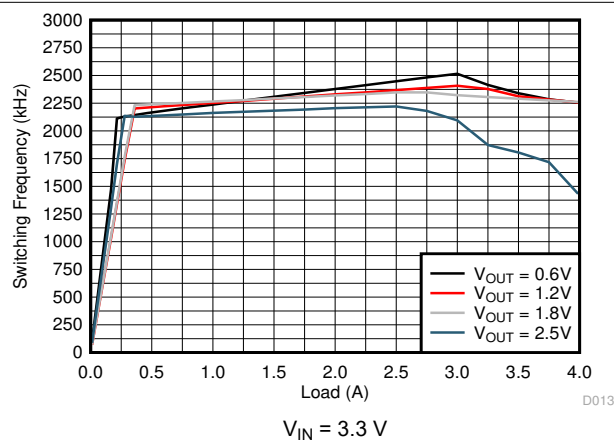


Figure 8-12. Switching Frequency

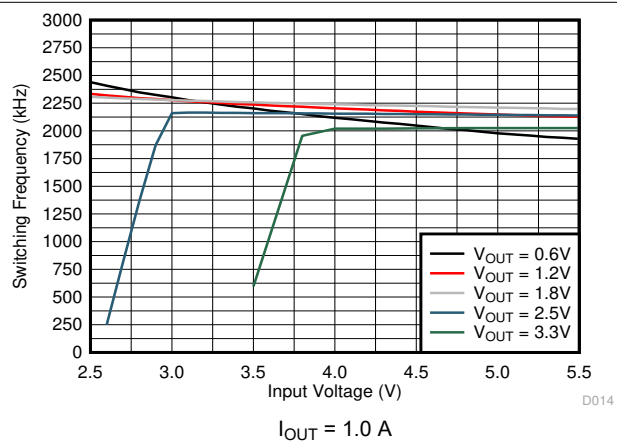


Figure 8-13. Switching Frequency

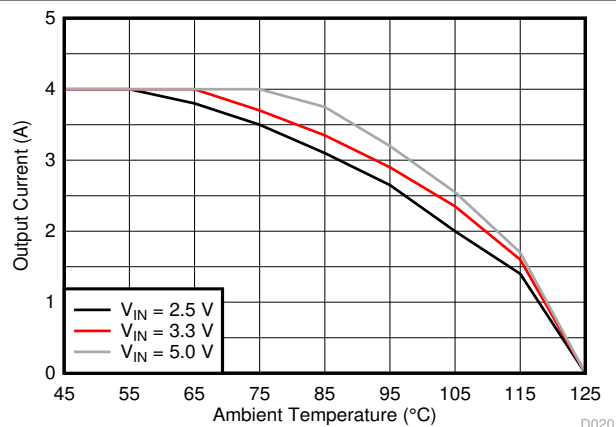


Figure 8-14. Thermal Derating

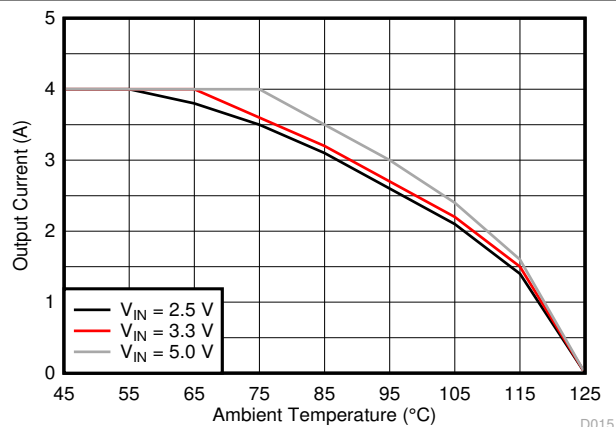


Figure 8-15. Thermal Derating

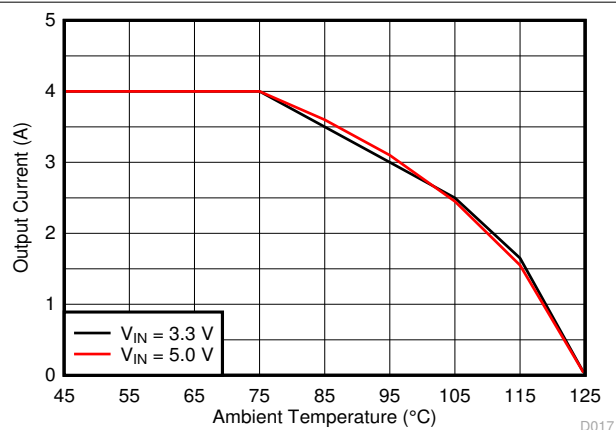


Figure 8-16. Thermal Derating

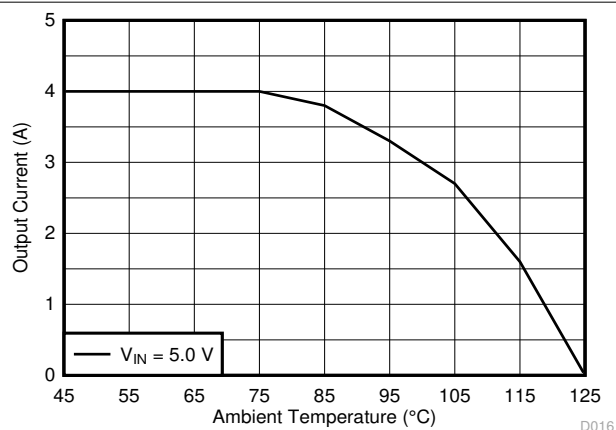


Figure 8-17. Thermal Derating

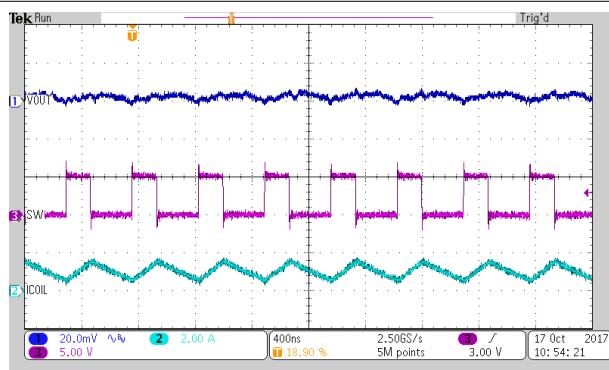


Figure 8-18. PWM Operation

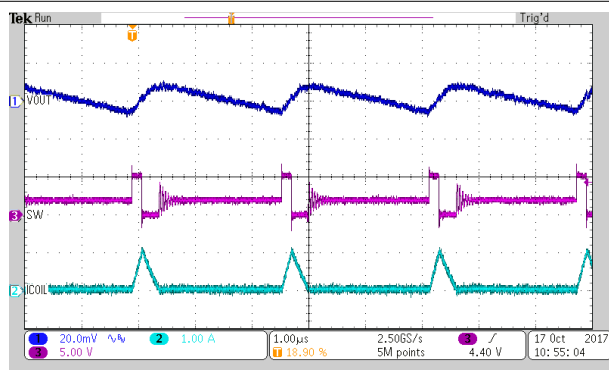


Figure 8-19. PSM Operation

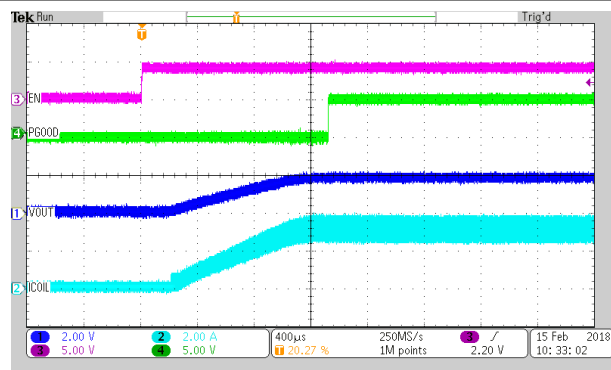
Load = 0.6 Ω

Figure 8-20. Start-up with Load

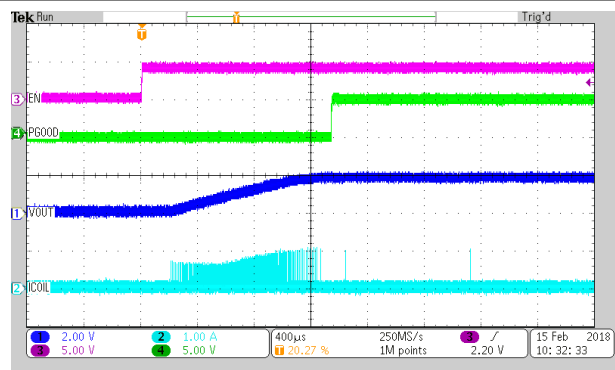


Figure 8-21. Startup with No Load

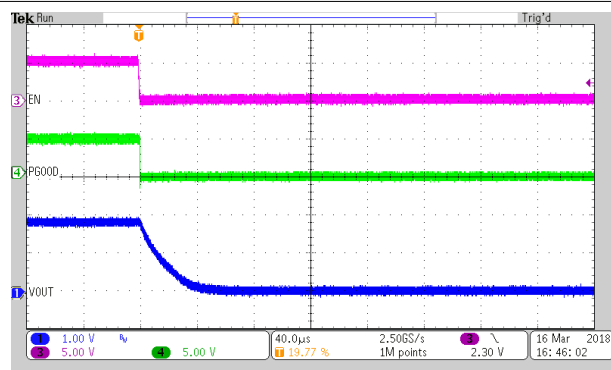
Load = 1.8 Ω

Figure 8-22. Disable, Active Output Discharge

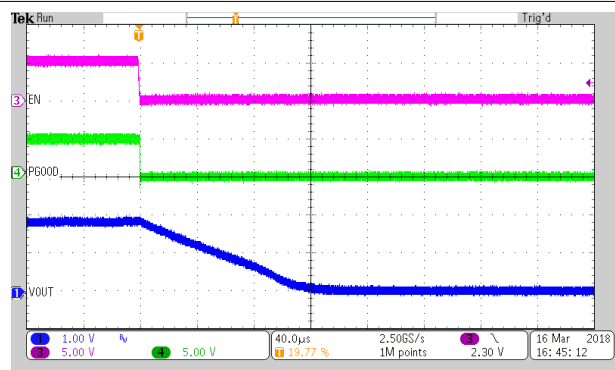


Figure 8-23. Disable, Active Output Discharge at No Load

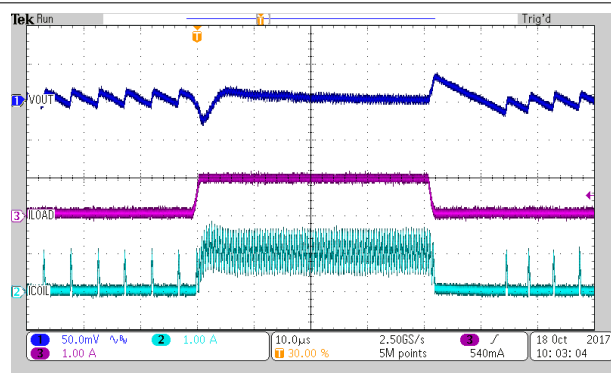
 I_{OUT} = 0.05 A to 1A

Figure 8-24. Load Transient

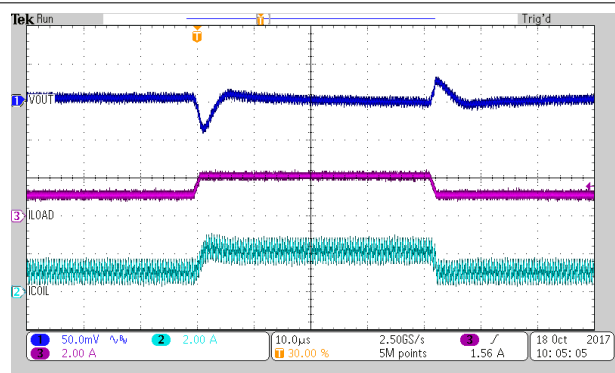
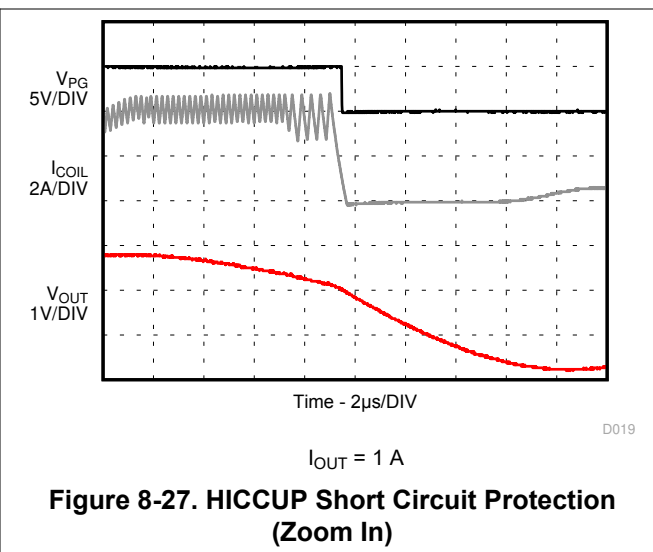
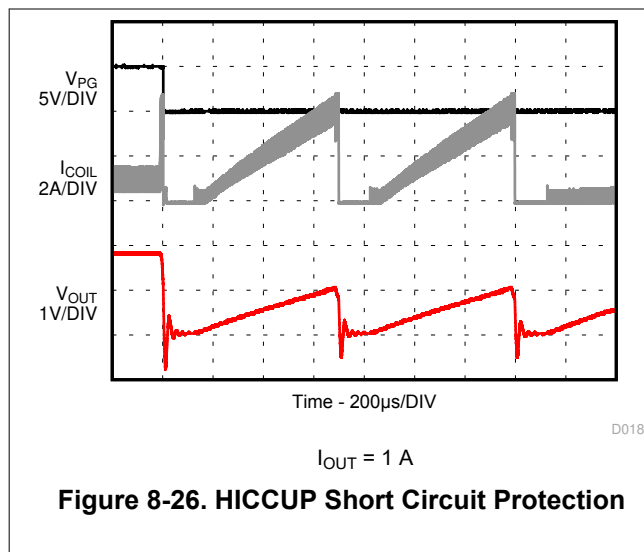
 I_{OUT} = 1 A to 2 A

Figure 8-25. Load Transient



8.3 Power Supply Recommendations

The device is designed to operate from an input voltage supply range from 2.4 V to 5.5 V. Ensure that the input power supply has a sufficient current rating for the application.

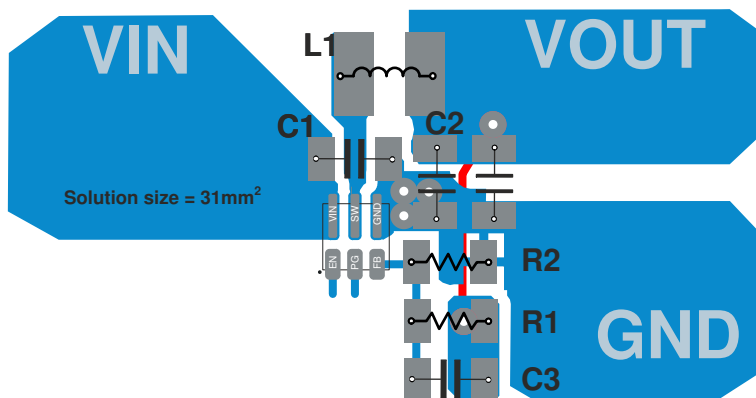
8.4 Layout

8.4.1 Layout Guidelines

The printed-circuit-board (PCB) layout is an important step to maintain the high performance of the device. See [Figure 8-28](#) for the recommended PCB layout.

- The input/output capacitors and the inductor must be placed as close as possible to the IC. This keeps the power traces short. Routing these power traces direct and wide results in low trace resistance and low parasitic inductance.
- The low side of the input and output capacitors must be connected properly to the GND pin to avoid a ground potential shift.
- The sense traces connected to FB is a signal trace. Special care must be taken to avoid noise being induced. Keep these traces away from SW nodes. The connection of the output voltage trace for the FB resistors must be made at the output capacitor.
- Refer to [Figure 8-28](#) for an example of component placement, routing and thermal design.

8.4.2 Layout Example



8.4.2.1 Thermal Considerations

Implementation of integrated circuits in low-profile and fine-pitch surface-mount packages typically requires special attention to power dissipation. Many system-dependent issues such as thermal coupling, airflow, added heat sinks and convection surfaces, and the presence of other heat-generating components affect the power dissipation limits of a given component.

Two basic approaches for enhancing thermal performance are:

- Improving the power dissipation capability of the PCB design
- Introducing airflow in the system

[Thermal Information](#) provides the thermal metric of the device on the EVM after considering the PCB design of real applications. The big copper planes connecting to the pads of the IC on the PCB improve the thermal performance of the device. For more details on how to use the thermal parameters, see the *Thermal Characteristics application notes*, [Thermal Characteristics of Linear and Logic Packages Using JEDEC PCB Designs](#) and [Semiconductor and IC Package Thermal Metrics](#).

9 Device and Documentation Support

9.1 Device Support

9.1.1 Third-Party Products Disclaimer

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9.1.2 Development Support

9.1.2.1 Custom Design With WEBENCH® Tools

[Click here](#) to create a custom design using the TLV62595 device with the WEBENCH® Power Designer.

1. Start by entering the input voltage (V_{IN}), output voltage (V_{OUT}), and output current (I_{OUT}) requirements.
2. Optimize the design for key parameters such as efficiency, footprint, and cost using the optimizer dial.
3. Compare the generated design with other possible solutions from Texas Instruments.

The WEBENCH Power Designer provides a customized schematic along with a list of materials with real-time pricing and component availability.

In most cases, these actions are available:

- Run electrical simulations to see important waveforms and circuit performance
- Run thermal simulations to understand board thermal performance
- Export customized schematic and layout into popular CAD formats
- Print PDF reports for the design, and share the design with colleagues

Get more information about WEBENCH tools at www.ti.com/WEBENCH.

9.2 Documentation Support

9.2.1 Related Documentation

For related documentation, see the following:

- Texas Instruments, [Thermal Characteristics of Linear and Logic Packages Using JEDEC PCB Designs](#) application note
- Texas Instruments, [Semiconductor and IC Package Thermal Metrics](#) application note

9.3 Receiving Notification of Documentation Updates

To receive notification of documentation updates, navigate to the device product folder on ti.com. Click on *Subscribe to updates* to register and receive a weekly digest of any product information that has changed. For change details, review the revision history included in any revised document.

9.4 Support Resources

[TI E2E™ support forums](#) are an engineer's go-to source for fast, verified answers and design help — straight from the experts. Search existing answers or ask your own question to get the quick design help you need.

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9.5 Trademarks

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9.6 Electrostatic Discharge Caution



This integrated circuit can be damaged by ESD. Texas Instruments recommends that all integrated circuits be handled with appropriate precautions. Failure to observe proper handling and installation procedures can cause damage.

ESD damage can range from subtle performance degradation to complete device failure. Precision integrated circuits may be more susceptible to damage because very small parametric changes could cause the device not to meet its published specifications.

9.7 Glossary

[TI Glossary](#) This glossary lists and explains terms, acronyms, and definitions.

10 Mechanical, Packaging, and Orderable Information

The following pages include mechanical, packaging, and orderable information. This information is the most current data available for the designated devices. This data is subject to change without notice and revision of this document. For browser-based versions of this data sheet, refer to the left-hand navigation.

PACKAGING INFORMATION

Orderable part number	Status (1)	Material type (2)	Package Pins	Package qty Carrier	RoHS (3)	Lead finish/ Ball material (4)	MSL rating/ Peak reflow (5)	Op temp (°C)	Part marking (6)
TLV62595DMQR	Active	Production	VSON-HR (DMQ) 6	3000 LARGE T&R	Yes	SN	Level-1-260C-UNLIM	-40 to 125	IM
TLV62595DMQR.A	Active	Production	VSON-HR (DMQ) 6	3000 LARGE T&R	Yes	SN	Level-1-260C-UNLIM	-40 to 125	IM

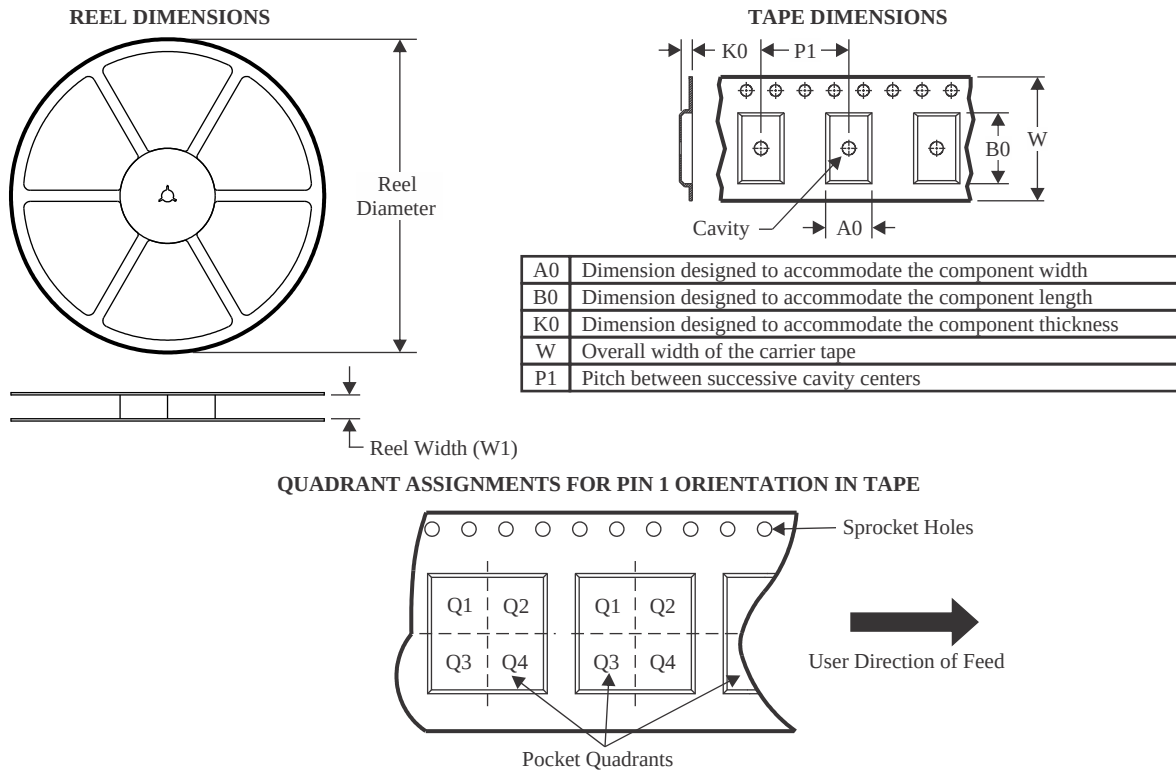
- ⁽¹⁾ **Status:** For more details on status, see our [product life cycle](#).
- ⁽²⁾ **Material type:** When designated, preproduction parts are prototypes/experimental devices, and are not yet approved or released for full production. Testing and final process, including without limitation quality assurance, reliability performance testing, and/or process qualification, may not yet be complete, and this item is subject to further changes or possible discontinuation. If available for ordering, purchases will be subject to an additional waiver at checkout, and are intended for early internal evaluation purposes only. These items are sold without warranties of any kind.
- ⁽³⁾ **RoHS values:** Yes, No, RoHS Exempt. See the [TI RoHS Statement](#) for additional information and value definition.
- ⁽⁴⁾ **Lead finish/Ball material:** Parts may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.
- ⁽⁵⁾ **MSL rating/Peak reflow:** The moisture sensitivity level ratings and peak solder (reflow) temperatures. In the event that a part has multiple moisture sensitivity ratings, only the lowest level per JEDEC standards is shown. Refer to the shipping label for the actual reflow temperature that will be used to mount the part to the printed circuit board.
- ⁽⁶⁾ **Part marking:** There may be an additional marking, which relates to the logo, the lot trace code information, or the environmental category of the part.

Multiple part markings will be inside parentheses. Only one part marking contained in parentheses and separated by a "~" will appear on a part. If a line is indented then it is a continuation of the previous line and the two combined represent the entire part marking for that device.

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In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

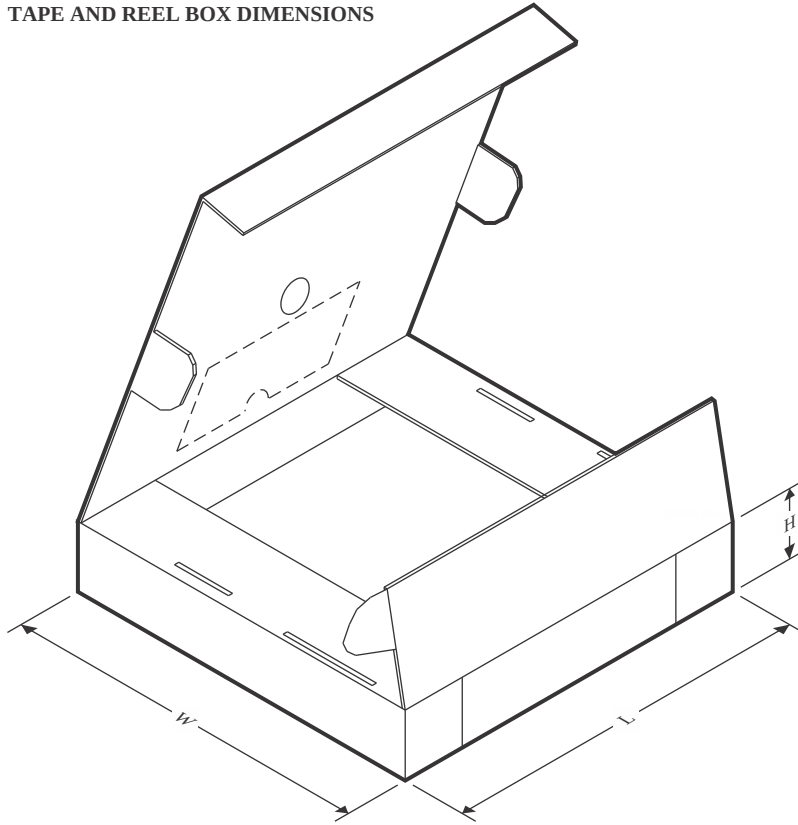
TAPE AND REEL INFORMATION



*All dimensions are nominal

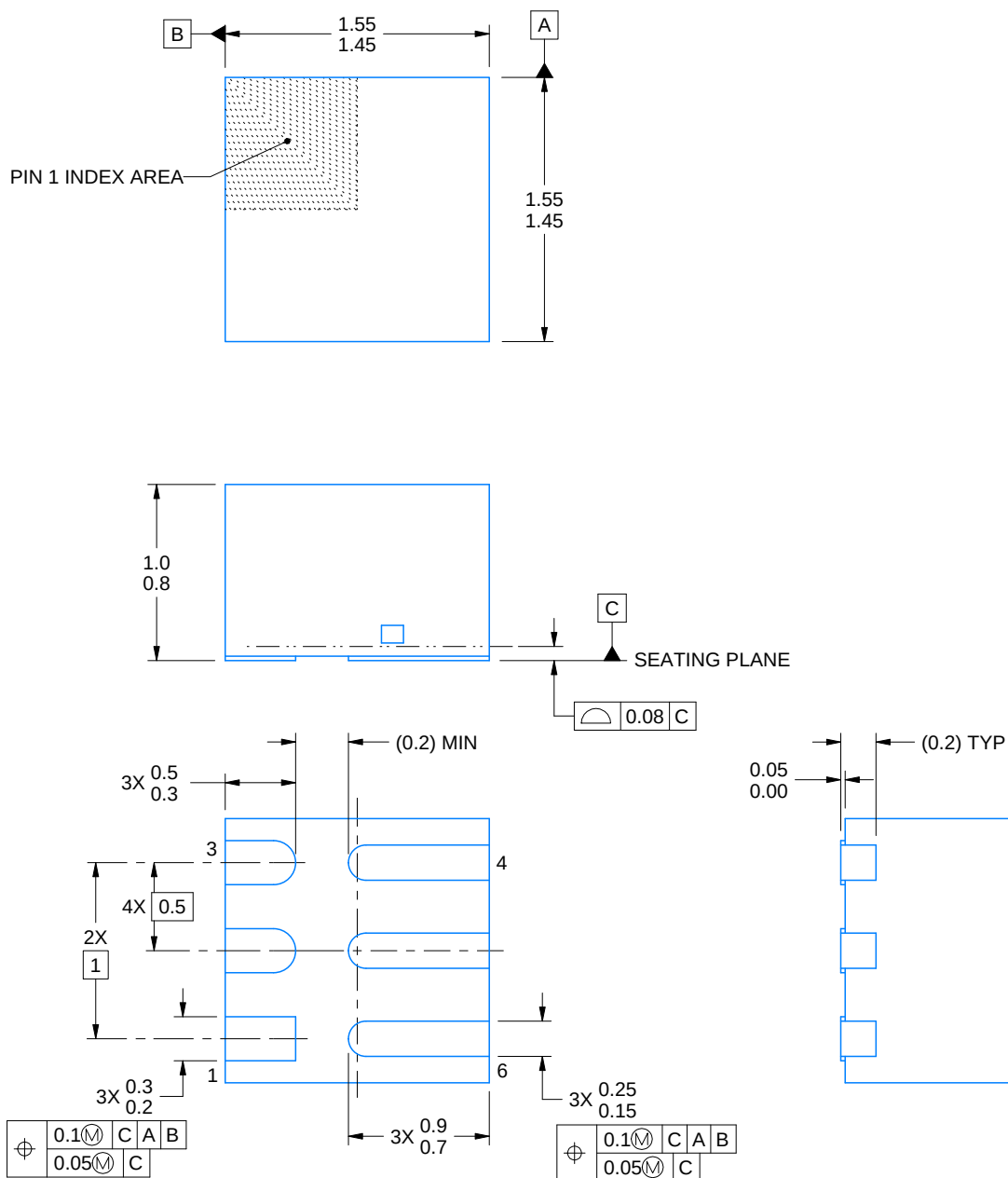
Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
TLV62595DMQR	VSON-HR	DMQ	6	3000	180.0	8.4	1.7	1.7	1.14	4.0	8.0	Q2

TAPE AND REEL BOX DIMENSIONS



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
TLV62595DMQR	VSON-HR	DMQ	6	3000	210.0	185.0	35.0



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NOTES:

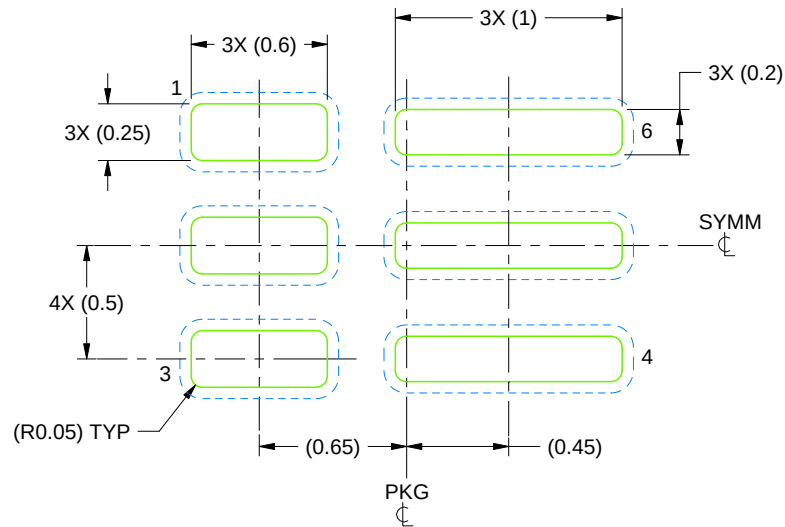
1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.

EXAMPLE BOARD LAYOUT

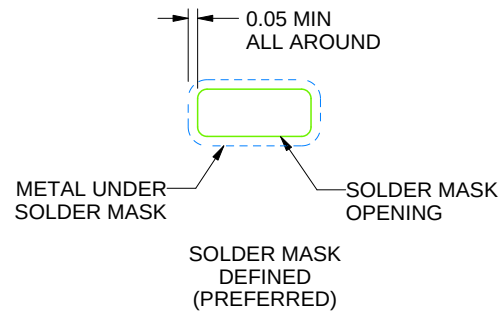
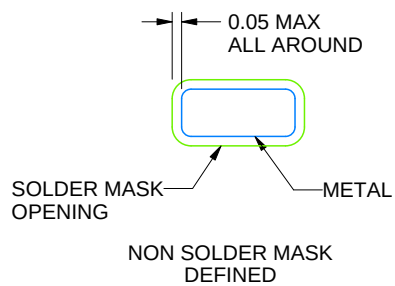
DMQ0006A

VSON - 1 mm max height

PLASTIC SMALL OUTLINE - NO LEAD



LAND PATTERN EXAMPLE
SCALE:30X



SOLDER MASK DETAILS

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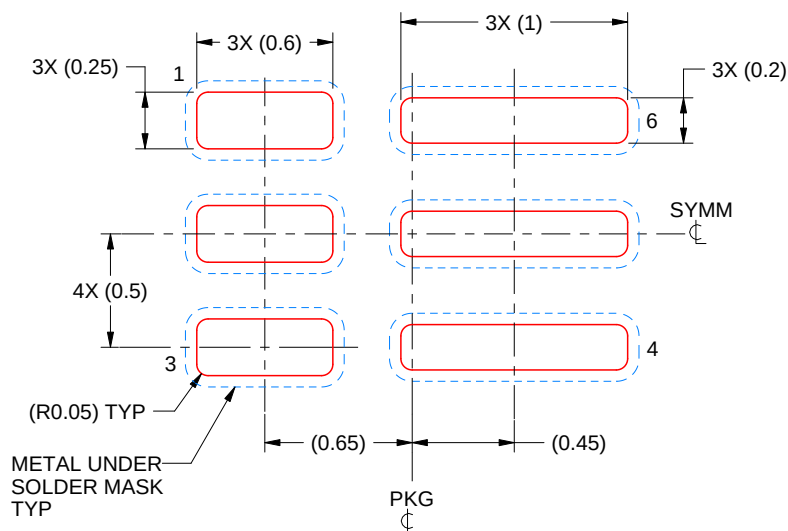
NOTES: (continued)

3. For more information, see Texas Instruments literature number SLUA271 (www.ti.com/lit/slua271).

DMQ0006A

VSON - 1 mm max height

PLASTIC SMALL OUTLINE - NO LEAD



SOLDER PASTE EXAMPLE
BASED ON 0.125 mm THICK STENCIL
SCALE:30X

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NOTES: (continued)

4. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.

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